

Zener Voltage Regulators

200 mW SOD-923 Surface Mount

This series of Zener diodes is packaged in a SOD-923 surface mount package. They are designed to provide voltage regulation protection and are especially attractive in situations where space is at a premium. They are well suited for applications such as cellular phones, hand held portables, and high density PC boards.

Specification Features:

- Standard Zener Breakdown Voltage Range – 2.4 V to 24 V
- Steady State Power Rating of 200 mW
- Small Body Outline Dimensions:
0.039" x 0.024" (1.00 mm x 0.60 mm)
- Low Body Height: 0.016" (0.40 mm)
- ESD Rating of Class 3 (>16 kV) per Human Body Model
- These are Pb-Free Devices
- S- Prefix for Automotive and Other Applications Requiring Unique Site and Control Change Requirements; AEC-Q101 Qualified and PPAP Capable.

Mechanical Characteristics:

CASE: Void-free, transfer-molded, thermosetting plastic

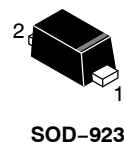
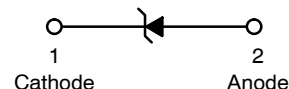
Epoxy Meets UL 94 V-0

LEAD FINISH: 100% Matte Sn (Tin)

MOUNTING POSITION: Any

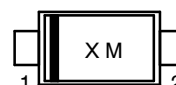
QUALIFIED MAX REFLOW TEMPERATURE: 260°C

Device Meets MSL 1 Requirements



SOD-923

MARKING DIAGRAM



X = Specific Device Code
M = Month Code

MAXIMUM RATINGS

Rating	Symbol	Max	Unit
Total Device Dissipation FR-5 Board, @ $T_A = 25^\circ\text{C}$	P_D	200	mW
Junction and Storage Temperature Range	T_J, T_{stg}	-65 to +150	$^\circ\text{C}$

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

ELECTRICAL CHARACTERISTICS

($T_A = 25^\circ\text{C}$ unless otherwise noted,
 $V_F = 0.9\text{ V Max. @ } I_F = 10\text{ mA}$ for all types)

Symbol	Parameter
V_Z	Reverse Zener Voltage @ I_{ZT}
I_{ZT}	Reverse Current
Z_{ZT}	Maximum Zener Impedance @ I_{ZT}
I_{ZK}	Reverse Current
Z_{ZK}	Maximum Zener Impedance @ I_{ZK}
I_R	Reverse Leakage Current @ V_R
V_R	Reverse Voltage
I_F	Forward Current
V_F	Forward Voltage @ I_F
ΘV_Z	Maximum Temperature Coefficient of V_Z
C	Max. Capacitance @ $V_R = 0$ and $f = 1\text{ MHz}$

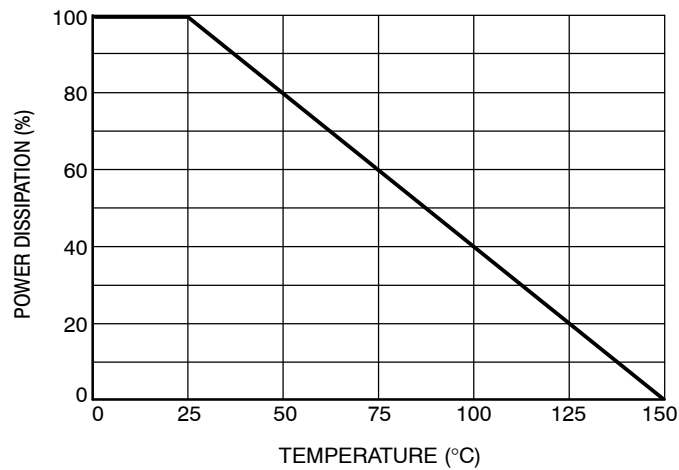
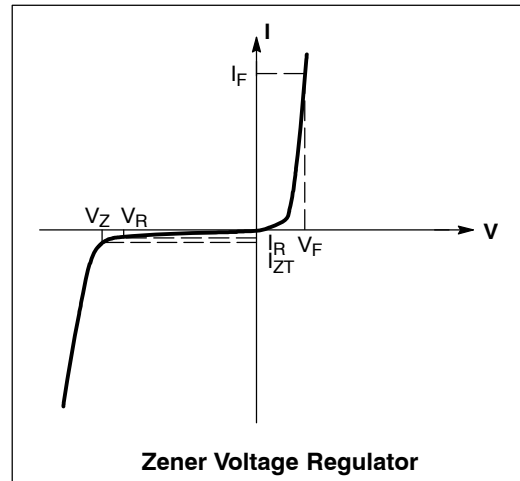


Figure 1. Steady State Power Derating

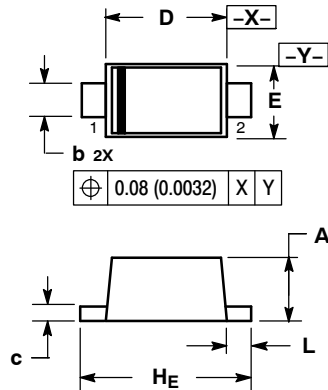
ELECTRICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$ unless otherwise noted, $V_F = 0.9\text{ V}$ Max. @ $I_F = 10\text{ mA}$ for all types)

Device	Device Marking	Zener Voltage (Note 1)			Zener Impedance			Leakage Current		θV_Z (mV/k) @ I_{ZT}		C @ $V_R = 0$ f = 1 MHz
		V_Z (Volts)		@ I_{ZT}	Z_{ZT} @ I_{ZT}	Z_{ZK} @ I_{ZK}		I_R @ V_R				
		Min	Max	mA	Ω	Ω	mA	μA	Volts	Min	Max	pF
NZ9F2V4	J	2.28	2.52	5	100	1000	1	50	1	-3.5	0	210
NZ9F2V7	E**	2.57	2.84	5	100	1000	1	20	1	-3.5	0	210
NZ9F3V0	T**	2.85	3.15	5	100	1000	1	10	1	-3.5	0	210
NZ9F3V3	Q	3.14	3.47	5	100	1000	1	10	1	-3.5	0	210
NZ9F3V6	3**	3.42	3.78	5	100	1000	1	10	1	-3.5	0	210
NZ9F3V9	V**	3.71	4.10	5	100	1000	1	5	1	-3.5	-2.5	210
NZ9F4V3	Y**	4.09	4.52	5	100	1000	1	5	1	-3.5	0	210
NZ9F4V7	3	4.47	4.94	5	100	800	0.5	2	1	-3.5	0.2	150
NZ9F5V1	4	4.85	5.36	5	80	500	0.5	2	1.5	-2.7	1.2	130
NZ9F5V6	5	5.32	5.88	5	60	200	0.5	1	2.5	-2.0	2.5	115
NZ9F6V2	6	5.89	6.51	5	60	100	0.5	1	3	0.4	3.7	110
NZ9F6V8	A*	6.46	7.14	5	40	60	0.5	0.5	3.5	1.2	4.5	105
NZ9F7V5	D*	7.13	7.88	5	30	60	0.5	0.5	4	2.5	5.3	100
NZ9F8V2	E*	7.79	8.61	5	30	60	0.5	0.5	5	3.2	6.2	90
NZ9F9V1	F*	8.65	9.56	5	30	60	0.5	0.5	6	3.8	7	80
NZ9F10V	J*	9.50	10.50	5	30	60	0.5	0.1	7	4.5	8	80
NZ9F11V	K*	10.45	11.55	5	30	60	0.5	0.1	8	5.4	9	80
NZ9F12V	L*	11.40	12.60	5	30	80	0.5	0.1	9	6	10	80
NZ9F13V	P*	12.35	13.65	5	37	80	0.5	0.1	10	7	11	75
NZ9F15V	Q*	14.25	15.75	5	42	80	0.5	0.1	11	9.2	13	70
NZ9F16V	R*	15.20	16.80	5	50	80	0.5	0.1	12	10.4	14	65
NZ9F18V	T*	17.10	18.90	5	50	80	0.5	0.1	14	12.4	16	60
NZ9F20V	V*	19.00	21.00	5	55	100	0.5	0.1	15.4	14.4	18	55
NZ9F22V	Y*	20.90	23.10	5	55	100	0.5	0.1	16.8	15.4	20	55
NZ9F24V	F	22.80	25.20	5	70	120	0.5	0.1	18.9	16.8	22	50

*Rotated 90° .**Rotated 270° .1. Zener voltage is measured with a pulse test current I_Z at an ambient temperature of 25°C .

PACKAGE DIMENSIONS

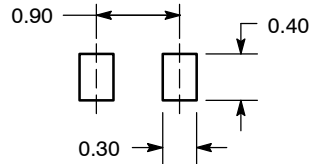
SOD-923



- NOTES:
1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M, 1982.
 2. CONTROLLING DIMENSION: MILLIMETERS.
 3. MAXIMUM LEAD THICKNESS INCLUDES LEAD FINISH THICKNESS. MINIMUM LEAD THICKNESS IS THE MINIMUM THICKNESS OF BASE MATERIAL.

DIM	MILLIMETERS			INCHES		
	MIN	NOM	MAX	MIN	NOM	MAX
A	0.34	0.37	0.40	0.013	0.015	0.016
b	0.15	0.20	0.25	0.006	0.008	0.010
c	0.07	0.12	0.17	0.003	0.005	0.007
D	0.75	0.80	0.85	0.030	0.031	0.033
E	0.55	0.60	0.65	0.022	0.024	0.026
H _E	0.95	1.00	1.05	0.037	0.039	0.041
L	0.05	0.10	0.15	0.002	0.004	0.006

SOLDERING FOOTPRINT*



DIMENSIONS: MILLIMETERS